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Applications of "<u>Embedded - Microcontrollers</u>"

B-4-9-	
Details	
Product Status	Obsolete
Core Processor	S08
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08re32cfge



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Pins and Connections

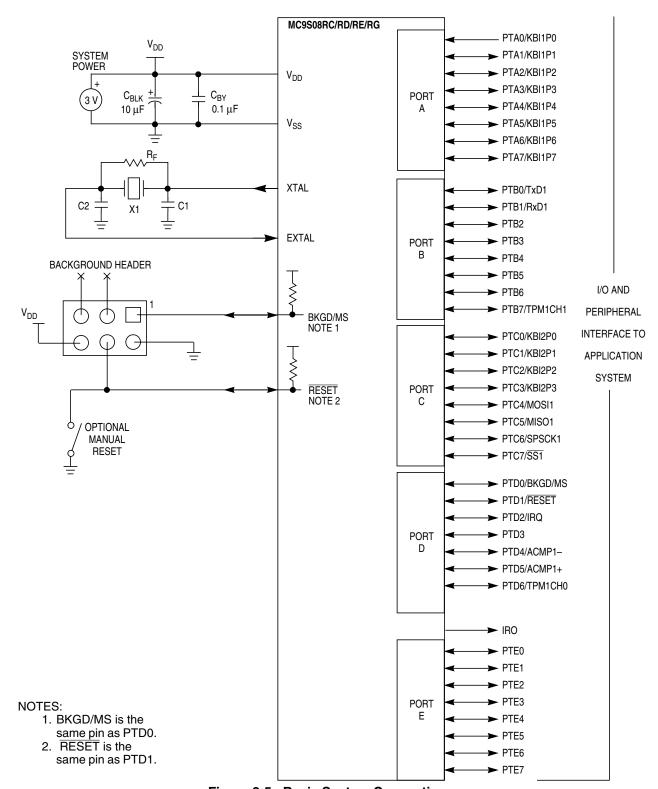


Figure 2-5. Basic System Connections

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Table 2-2. Signal Properties (continued)

Pin Name	Dir ⁽¹⁾	High Current Pin	Pullup ⁽²⁾	Comments ⁽³⁾
PTD2/IRQ	I/O	N	SWC ⁽⁵⁾	Available only in 32-, 44-, and 48-pin packagess
PTD3	I/O	N	SWC	Available only in 44- and 48-pin packages
PTD4/ACMP1-	I/O	N	SWC	Available only in 32-, 44-, and 48-pin packagess
PTD5/ACMP1+	I/O	N	SWC	Available only in 32-, 44-, and 48-pin packagess
PTD6/TPM1CH0	I/O	N	SWC	
PTE0	I/O	N	SWC	Available only in 44- and 48-pin packages
PTE1	I/O	N	SWC	Available only in 44- and 48-pin packages
PTE2	I/O	N	SWC	Available only in 44- and 48-pin packages
PTE3	I/O	N	SWC	Available only in 44- and 48-pin packages
PTE4	I/O	N	SWC	Available only in 44- and 48-pin packages
PTE5	I/O	N	SWC	Available only in 44- and 48-pin packages
PTE6	I/O	N	SWC	Available only in 44- and 48-pin packages
PTE7	I/O	N	SWC	Available only in 44- and 48-pin packages

- 1. Unless otherwise indicated, all digital inputs have input hysteresis.
- 2. SWC is software-controlled pullup resistor, the register is associated with the respective port.
- 3. Not all general-purpose I/O pins are available on all packages. To avoid extra current drain from floating input pins, the user's reset initialization routine in the application program should either enable on-chip pullup devices or change the direction of unconnected pins to outputs so the pins do not float.
- 4. When these pins are configured as RESET or BKGD/MS pullup device is enabled.
- 5. When configured for the IRQ function, this pin will have a pullup device enabled when the IRQ is set for falling edge detection and a pulldown device enabled when the IRQ is set for rising edge detection.

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3.6.4 Active BDM Enabled in Stop Mode

Entry into the active background mode from run mode is enabled if the ENBDM bit in BDCSCR is set. This register is described in the Development Support chapter of this data sheet. If ENBDM is set when the CPU executes a STOP instruction, the system clocks to the background debug logic remain active when the MCU enters stop mode so background debug communication is still possible. In addition, the voltage regulator does not enter its low-power standby state but maintains full internal regulation. The MCU cannot enter either stop1 mode or stop2 mode if ENBDM is set.

Most background commands are not available in stop mode. The memory-access-with-status commands do not allow memory access, but they report an error indicating that the MCU is in either stop or wait mode. The BACKGROUND command can be used to wake the MCU from stop and enter active background mode if the ENBDM bit is set. After active background mode is entered, all background commands are available. Table 3-2 summarizes the behavior of the MCU in stop when entry into the active background mode is enabled.

Mode	PDC	PPDC	CPU, Digital Peripherals, FLASH	RAM	osc	АСМР	Regulator	I/O Pins	RTI
Stop3	Don't care	Don't care	Standby	Standby	On	Standby	On	States held	Optionally on

Table 3-2. BDM Enabled Stop Mode Behavior

3.6.5 LVD Reset Enabled

The LVD system is capable of generating either an interrupt or a reset when the supply voltage drops below the LVD voltage. If the LVD reset is enabled in stop by setting the LVDRE bit in SPMSC1 when the CPU executes a STOP instruction, then the voltage regulator remains active during stop mode. If the user attempts to enter either stop1 or stop2 with the LVD reset enabled (LVDRE = 1) the MCU will instead enter stop3. Table 3-3 summarizes the behavior of the MCU in stop when LVD reset is enabled.

Mode	PDC	PPDC	CPU, Digital Peripherals, FLASH	RAM	osc	АСМР	Regulator	I/O Pins	RTI
Stop3	Don't care	Don't care	Standby	Standby	On	Standby	On	States held	Optionally on

Table 3-3. LVD Enabled Stop Mode Behavior

3.6.6 **On-Chip Peripheral Modules in Stop Mode**

When the MCU enters any stop mode, system clocks to the internal peripheral modules are stopped. Even in the exception case (ENBDM = 1), where clocks are kept alive to the background debug logic, clocks to the peripheral systems are halted to reduce power consumption.

MC9S08RC/RD/RE/RG Data Sheet, Rev. 1.11



Memory

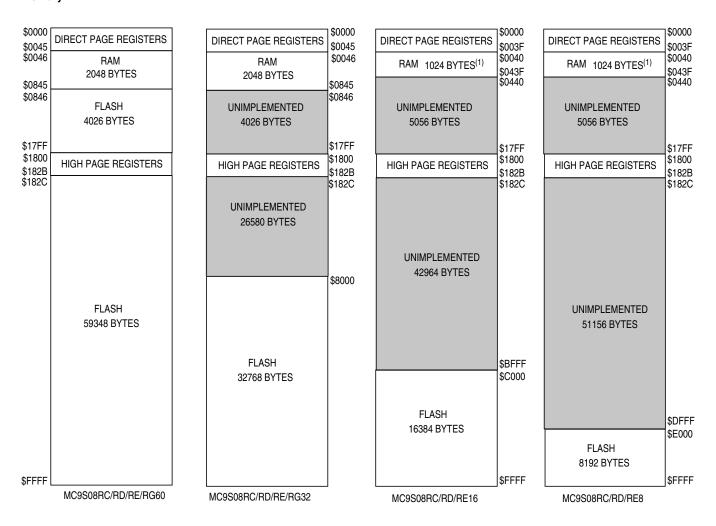


Figure 4-1. MC9S08RC/RD/RE/RG Memory Map

4.1.1 Reset and Interrupt Vector Assignments

Figure 4-2 shows address assignments for reset and interrupt vectors. The vector names shown in this table are the labels used in the Freescale-provided equate file for the MC9S08RC/RD/RE/RG. For more details about resets, interrupts, interrupt priority, and local interrupt mask controls, refer to the Chapter 5, "Resets, Interrupts, and System Configuration."



Resets, Interrupts, and System Configuration

_	7	6	5	4	3	2	1	0
R	POR	PIN	COP	ILOP	ILAD ⁽¹⁾	0	LVD	0
w		Wr	iting any value	to SRS addre	ess clears COF	watchdog tim	ner.	
POR	1	0	0	0	0	0	1	0
LVR	u	0	0	0	0	0	1	0
Any other reset:	0	(2)	(2)	(2)	(2)	0	0	0

u = Unaffected by reset

Figure 5-3. System Reset Status (SRS)

- 1. The ILAD bit is only present in 16K and 8K versions of the devices.
- 2. Any of these reset sources that are active at the time of reset will cause the corresponding bit(s) to be set; bits corresponding to sources that are not active at the time of reset will be cleared.

Table 5-3. SRS Field Descriptions

Field	Description
7 POR	Power-On Reset — Reset was caused by the power-on detection logic. Because the internal supply voltage was ramping up at the time, the low-voltage reset (LVR) status bit is also set to indicate that the reset occurred while the internal supply was below the LVR threshold. O Reset not caused by POR. 1 POR caused reset.
6 PIN	External Reset Pin — Reset was caused by an active-low level on the external reset pin. O Reset not caused by external reset pin. Reset came from external reset pin.
5 COP	Computer Operating Properly (COP) Watchdog — Reset was caused by the COP watchdog timer timing out. This reset source may be blocked by COPE = 0. Reset not caused by COP timeout. Reset caused by COP timeout.
4 ILOP	Illegal Opcode — Reset was caused by an attempt to execute an unimplemented or illegal opcode. The STOP instruction is considered illegal if stop is disabled by STOPE = 0 in the SOPT register. The BGND instruction is considered illegal if active background mode is disabled by ENBDM = 0 in the BDCSC register. O Reset not caused by an illegal opcode. Reset caused by an illegal opcode.
3 ILAD	Illegal Address Access — Reset was caused by an attempt to access a designated illegal address. O Reset not caused by an illegal address access Reset caused by an illegal address access Illegal address areas only exist in the 16K and 8K versions and are defined as: • \$0440-\$17FF — Gap from end of RAM to start of high-page registers • \$1834-\$BFFF — Gap from end of high-page registers to start of FLASH memory Unused and reserved locations in register areas are not considered designated illegal addresses and do not trigger illegal address resets.
1 LVD	Low Voltage Detect — If the LVDRE bit is set and the supply drops below the LVD trip voltage, an LVD reset occurs. This bit is also set by POR. 0 Reset not caused by LVD trip or POR 1 Reset caused by LVD trip or POR

MC9S08RC/RD/RE/RG Data Sheet, Rev. 1.11

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Central Processor Unit (S08CPUV2)Central Processor Unit (S08CPUV2)

Table 7-2. HCS08 Instruction Set Summary (Sheet 6 of 7)

Source	Onerstien	Department				fec CC			ess de	ope	and	/cles ¹
Form	Operation	Description	v	н	ı	N	z	С	Address	Opcode	Operand	Bus Cycles ¹
ROR opr8a RORA RORX ROR oprx8,X ROR ,X ROR oprx8,SP	Rotate Right through Carry	b7 b0		_	_				DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	ff	5 1 1 5 4 6
RSP	Reset Stack Pointer	SP ← 0xFF (High Byte Not Affected)	-	-	-	-	-	-	INH	9C		1
RTI	Return from Interrupt	$\begin{array}{c} SP \leftarrow (SP) + 0x0001; \ Pull \ (CCR) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (A) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (X) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (PCH) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (PCL) \end{array}$							INH	80		9
RTS	Return from Subroutine	SP ← SP + 0x0001; Pull (PCH) SP ← SP + 0x0001; Pull (PCL)	-	-	-	-	-	-	INH	81		6
SBC #opr8i SBC opr8a SBC opr16a SBC oprx16,X SBC oprx8,X SBC ,X SBC oprx16,SP SBC oprx8,SP	Subtract with Carry	$A \leftarrow (A) - (M) - (C)$		_	_				IMM DIR EXT IX2 IX1 IX SP2 SP1		dd hh II ee ff ff	2 3 4 4 3 3 5 4
SEC	Set Carry Bit	C ← 1	-	_	-	-	-	1	INH	99		1
SEI	Set Interrupt Mask Bit	I ← 1	-	_	1	-	-	-	INH	9B		1
STA opr8a STA opr16a STA oprx16,X STA oprx8,X STA ,X STA oprx16,SP STA oprx8,SP	Store Accumulator in Memory	M ← (A)	0	_	_			-	DIR EXT IX2 IX1 IX SP2 SP1		hh II ee ff ff ee ff	3 4 4 3 2 5 4
STHX opr8a STHX opr16a STHX oprx8,SP	Store H:X (Index Reg.)	(M:M + 0x0001) ← (H:X)	0	-	-			-	DIR EXT SP1	35 96 9EFF	hh II	4 5 5
STOP	Enable Interrupts: Stop Processing Refer to MCU Documentation	I bit ← 0; Stop Processing	_	_	0	_	-	-	INH	8E		2+
STX opr8a STX opr16a STX oprx16,X STX oprx8,X STX ,X STX oprx16,SP STX oprx8,SP	Store X (Low 8 Bits of Index Register) in Memory	$M \leftarrow (X)$	0	_	_			-	DIR EXT IX2 IX1 IX SP2 SP1		hh II ee ff ff	3 4 4 3 2 5 4
SUB #opr8i SUB opr8a SUB opr16a SUB oprx16,X SUB oprx8,X SUB ,X SUB ,X SUB oprx16,SP SUB oprx8,SP	Subtract	A ← (A) − (M)		_	_				IMM DIR EXT IX2 IX1 IX SP2 SP1		dd hh II ee ff ff	2 3 4 4 3 3 5 4
SWI	Software Interrupt	$\begin{array}{c} PC \leftarrow (PC) + 0x0001 \\ Push \; (PCL); \; SP \leftarrow (SP) - 0x0001 \\ Push \; (PCH); \; SP \leftarrow (SP) - 0x0001 \\ Push \; (X); \; SP \leftarrow (SP) - 0x0001 \\ Push \; (A); \; SP \leftarrow (SP) - 0x0001 \\ Push \; (CCR); \; SP \leftarrow (SP) - 0x0001 \\ I \leftarrow I; \\ PCH \leftarrow Interrupt \; Vector \; High \; Byte \\ PCL \leftarrow Interrupt \; Vector \; Low \; Byte \\ \end{array}$	_	_	1	_	_	-	INH	83		11

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8.5.5 CMT Interrupts

The end of cycle flag (EOCF) is set when:

- The modulator is not currently active and the MCGEN bit is set to begin the initial CMT transmission
- At the end of each modulation cycle (when the counter is reloaded from CMTCMD1:CMTCMD2) while the MCGEN bit is set

In the case where the MCGEN bit is cleared and then set before the end of the modulation cycle, the EOCF bit will not be set when the MCGEN is set, but will become set at the end of the current modulation cycle.

When the MCGEN becomes disabled, the CMT module does not set the EOC flag at the end of the last modulation cycle.

The EOCF bit is cleared by reading the CMT modulator status and control register (CMTMSC) followed by an access of CMTCMD2 or CMTCMD4.

If the EOC interrupt enable (EOCIE) bit is high when the EOCF bit is set, the CMT module will generate an interrupt request. The EOCF bit must be cleared within the interrupt service routine to prevent another interrupt from being generated after exiting the interrupt service routine.

The EOC interrupt is coincident with loading the down-counter with the contents of CMTCMD1:CMTCMD2 and loading the space period register with the contents of CMTCMD3:CMTCMD4. The EOC interrupt provides a means for the user to reload new mark/space values into the modulator data registers. Modulator data register updates will take effect at the end of the current modulation cycle. Note that the down-counter and space period register are updated at the end of every modulation cycle, regardless of interrupt handling and the state of the EOCF flag.

8.5.6 Wait Mode Operation

During wait mode the CMT, if enabled, will continue to operate normally. However, there will be no new codes or changes of pattern mode while in wait mode, because the CPU is not operating.

8.5.7 Stop Mode Operation

During all stop modes, clocks to the CMT module are halted.

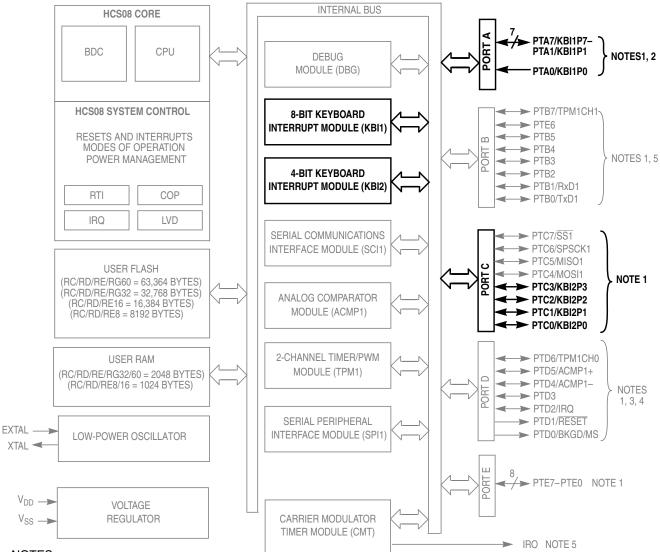
In stop1 and stop2 modes, all CMT register data is lost and must be re-initialized upon recovery from these two stop modes.

No CMT module registers are affected in stop3 mode.

Note, because the clocks are halted, the CMT will resume upon exit from stop (only in stop3 mode). Software should ensure stop2 or stop3 mode is not entered while the modulator is in operation to prevent the IRO pin from being asserted while in stop mode. This may require a time-out period from the time that the MCGEN bit is cleared to allow the last modulator cycle to complete.



Keyboard Interrupt (S08KBIV1)



- NOTES:

 - 7. Port pins are software configurable with pullup device if input port 8. PTA0 does not have a clamp diode to V_{DD} . PTA0 should not be driven above V_{DD} . Also, PTA0 does not pullup to V_{DD} when internal pullup is enabled.
 - IRQ pin contains software configurable pullup/pulldown device if IRQ enabled (IRQPE = 1) 10. The RESET pin contains integrated pullup device enabled if reset enabled (RSTPE = 1)
 - 11. High current drive
 - 11. Pins PTA[7:4] contain both pullup and pulldown devices. Pulldown enabled when KBI is enabled (KBIPEn = 1) and rising edge is selected (KBEDGn = 1).

Figure 9-1. MC9S08RC/RD/RE/RG Block Diagram



Chapter 10 Timer/PWM Module (S08TPMV1)

10.1 Introduction

The MC9S08RC/RD/RE/RG includes a timer/PWM (TPM) module that supports traditional input capture, output compare, or buffered edge-aligned pulse-width modulation (PWM) on each channel. A control bit in the TPM configures both channels in the timer to operate as center-aligned PWM functions. Timing functions in the TPM are based on a 16-bit counter with prescaler and modulo features to control frequency and range (period between overflows) of the time reference. This timing system is ideally suited for a wide range of control applications. The MC9S08RC/RD/RE/RG devices do not have a separate fixed internal clock source (XCLK). If the XCLK source is selected using the CLKSA and CLKSB control bits (see Table 10-2), the TPM will use the BUSCLK.

10.2 Features

Timer system features include:

- Two separate channels:
 - Each channel may be input capture, output compare, or buffered edge-aligned PWM
 - Rising-edge, falling-edge, or any-edge input capture trigger
 - Set, clear, or toggle output compare action
 - Selectable polarity on PWM outputs
- The TPM may be configured for buffered, center-aligned pulse-width modulation (CPWM) on both channels
- Clock source to prescaler for the TPM is selectable between the bus clock or an external pin:
 - Prescale taps for divide by 1, 2, 4, 8, 16, 32, 64, or 128
 - External clock input shared with TPM1CH0 timer channel pin
- 16-bit modulus register to control counter range
- Timer system enable
- One interrupt per channel plus terminal count interrupt



Chapter 12 Serial Communications Interface (S08SCIV1)

12.1 Introduction

12.1.1 Features

Features of SCI module include:

- Full-duplex, standard non-return-to-zero (NRZ) format
- Double-buffered transmitter and receiver with separate enables
- Programmable baud rates (13-bit modulo divider)
- Interrupt-driven or polled operation:
 - Transmit data register empty and transmission complete
 - Receive data register full
 - Receive overrun, parity error, framing error, and noise error
 - Idle receiver detect
- Hardware parity generation and checking
- Programmable 8-bit or 9-bit character length
- Receiver wakeup by idle-line or address-mark

12.1.2 Modes of Operation

See Section 12.3, "Functional Description," for a detailed description of SCI operation in the different modes.

- 8- and 9- bit data modes
- Stop modes SCI is halted during all stop modes
- Loop modes



Serial Communications Interface (S08SCIV1)

internally connected to the receiver input and the RxD1 pin is not used by the SCI, so it reverts to a general-purpose port I/O pin.

12.3.5.4 Single-Wire Operation

When LOOPS = 1, the RSRC bit in the same register chooses between loop mode (RSRC = 0) or single-wire mode (RSRC = 1). Single-wire mode is used to implement a half-duplex serial connection. The receiver is internally connected to the transmitter output and to the TxD1 pin. The RxD1 pin is not used and reverts to a general-purpose port I/O pin.

In single-wire mode, the TXDIR bit in SCI1C3 controls the direction of serial data on the TxD1 pin. When TXDIR = 0, the TxD1 pin is an input to the SCI receiver and the transmitter is temporarily disconnected from the TxD1 pin so an external device can send serial data to the receiver. When TXDIR = 1, the TxD1 pin is an output driven by the transmitter. In single-wire mode, the internal loop back connection from the transmitter to the receiver causes the receiver to receive characters that are sent out by the transmitter.



Serial Peripheral Interface (SPI) Module

13.4.1 SPI Control Register 1 (SPI1C1)

This read/write register includes the SPI enable control, interrupt enables, and configuration options.

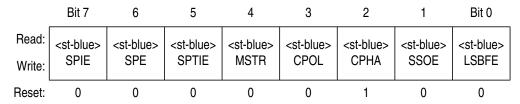


Figure 13-7. SPI Control Register 1 (SPI1C1)

SPIE — SPI Interrupt Enable (for SPRF and MODF)

This is the interrupt enable for SPI receive buffer full (SPRF) and mode fault (MODF) events.

- 1 = When SPRF or MODF is 1, request a hardware interrupt.
- 0 = Interrupts from SPRF and MODF inhibited (use polling).

SPE — SPI System Enable

Disabling the SPI halts any transfer that is in progress, clears data buffers, and initializes internal state machines. SPRF is cleared and SPTEF is set to indicate the SPI transmit data buffer is empty.

- 1 = SPI system enabled.
- 0 = SPI system inactive.

SPTIE — SPI Transmit Interrupt Enable

This is the interrupt enable bit for SPI transmit buffer empty (SPTEF).

- 1 = When SPTEF is 1, hardware interrupt requested.
- 0 = Interrupts from SPTEF inhibited (use polling).

MSTR — Master/Slave Mode Select

- 1 = SPI module configured as a master SPI device.
- 0 = SPI module configured as a slave SPI device.

CPOL — Clock Polarity

This bit effectively places an inverter in series with the clock signal from a master SPI or to a slave SPI device. Refer to Section 13.3.1, "SPI Clock Formats," for more details.

- 1 = Active-low SPI clock (idles high).
- 0 = Active-high SPI clock (idles low).

CPHA — Clock Phase

This bit selects one of two clock formats for different kinds of synchronous serial peripheral devices. Refer to Section 13.3.1, "SPI Clock Formats," for more details.

- 1 = First edge on SPSCK occurs at the start of the first cycle of an 8-cycle data transfer.
- 0 = First edge on SPSCK occurs at the middle of the first cycle of an 8-cycle data transfer.



14.4 Functional Description

The analog comparator can be used to compare two analog input voltages applied to ACMP1– and ACMP1+; or it can be used to compare an analog input voltage applied to ACMP1– with an internal bandgap reference voltage. The ACBGS bit is used to select the mode of operation. The comparator output is high when the non-inverting input is greater than the inverting input, and is low when the non-inverting input is less than the inverting input. The ACMOD0 and ACMOD1 bits are used to select the condition that will cause the ACF bit to be set. The ACF bit can be set on a rising edge of the comparator output, a falling edge of the comparator output, or either a rising or a falling edge. The comparator output can be read directly through the ACO bit.

14.4.1 Interrupts

The ACMP module is capable of generating an interrupt on a compare event. The interrupt request is asserted when both the ACIE bit and the ACF bit are set. The interrupt is deasserted by clearing either the ACIE bit or the ACF bit. The ACIE bit is cleared by writing a 0 and the ACF bit is cleared by writing a 1.

14.4.2 Wait Mode Operation

During wait mode the ACMP, if enabled, will continue to operate normally. Also, if enabled, the interrupt can wake up the MCU.

14.4.3 Stop Mode Operation

During stop mode, clocks to the ACMP module are halted. The ACMP comparator circuit will enter a low power state. No compare operation will occur while in stop mode.

In stop1 and stop2 modes, the ACMP module will be in its reset state when the MCU recovers from the stop condition and must be re-initialized.

In stop3 mode, control and status register information is maintained and upon recovery normal ACMP function is available to the user.

14.4.4 Background Mode Operation

When the microcontroller is in active background mode, the ACMP will continue to operate normally.



Development Support

Figure 15-2 shows an external host transmitting a logic 1 or 0 to the BKGD pin of a target HCS08 MCU. The host is asynchronous to the target so there is a 0-to-1 cycle delay from the host-generated falling edge to where the target perceives the beginning of the bit time. Ten target BDC clock cycles later, the target senses the bit level on the BKGD pin. Typically, the host actively drives the pseudo-open-drain BKGD pin during host-to-target transmissions to speed up rising edges. Because the target does not drive the BKGD pin during the host-to-target transmission period, there is no need to treat the line as an open-drain signal during this period.

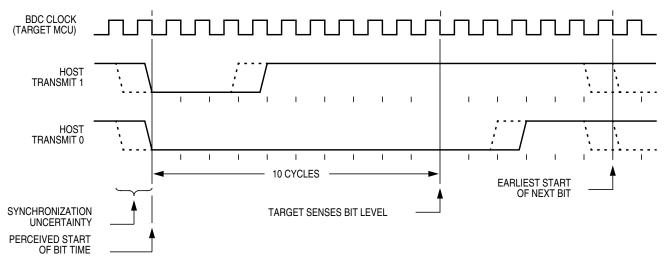


Figure 15-2. BDC Host-to-Target Serial Bit Timing

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Development Support

15.3 On-Chip Debug System (DBG)

Because HCS08 devices do not have external address and data buses, the most important functions of an in-circuit emulator have been built onto the chip with the MCU. The debug system consists of an 8-stage FIFO that can store address or data bus information, and a flexible trigger system to decide when to capture bus information and what information to capture. The system relies on the single-wire background debug system to access debug control registers and to read results out of the eight stage FIFO.

The debug module includes control and status registers that are accessible in the user's memory map. These registers are located in the high register space to avoid using valuable direct page memory space.

Most of the debug module's functions are used during development, and user programs rarely access any of the control and status registers for the debug module. The one exception is that the debug system can provide the means to implement a form of ROM patching. This topic is discussed in greater detail in Section 15.3.6, "Hardware Breakpoints."

15.3.1 Comparators A and B

Two 16-bit comparators (A and B) can optionally be qualified with the R/W signal and an opcode tracking circuit. Separate control bits allow you to ignore R/W for each comparator. The opcode tracking circuitry optionally allows you to specify that a trigger will occur only if the opcode at the specified address is actually executed as opposed to only being read from memory into the instruction queue. The comparators are also capable of magnitude comparisons to support the inside range and outside range trigger modes. Comparators are disabled temporarily during all BDC accesses.

The A comparator is always associated with the 16-bit CPU address. The B comparator compares to the CPU address or the 8-bit CPU data bus, depending on the trigger mode selected. Because the CPU data bus is separated into a read data bus and a write data bus, the RWAEN and RWA control bits have an additional purpose, in full address plus data comparisons they are used to decide which of these buses to use in the comparator B data bus comparisons. If RWAEN = 1 (enabled) and RWA = 0 (write), the CPU's write data bus is used. Otherwise, the CPU's read data bus is used.

The currently selected trigger mode determines what the debugger logic does when a comparator detects a qualified match condition. A match can cause:

- Generation of a breakpoint to the CPU
- Storage of data bus values into the FIFO
- Starting to store change-of-flow addresses into the FIFO (begin type trace)
- Stopping the storage of change-of-flow addresses into the FIFO (end type trace)

15.3.2 Bus Capture Information and FIFO Operation

The usual way to use the FIFO is to setup the trigger mode and other control options, then arm the debugger. When the FIFO has filled or the debugger has stopped storing data into the FIFO, you would read the information out of it in the order it was stored into the FIFO. Status bits indicate the number of words of valid information that are in the FIFO as data is stored into it. If a trace run is manually halted by writing 0 to ARM before the FIFO is full (CNT = 1:0:0:0), the information is shifted by one position and

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15.4.3.9 Debug Status Register (DBGS)

This is a read-only status register.

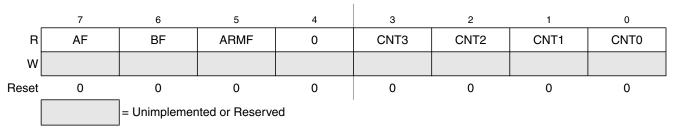


Figure 15-9. Debug Status Register (DBGS)

Table 15-6. DBGS Register Field Descriptions

Field	Description						
7 AF	Trigger Match A Flag — AF is cleared at the start of a debug run and indicates whether a trigger match A condition was met since arming. O Comparator A has not matched Comparator A match						
6 BF	Trigger Match B Flag — BF is cleared at the start of a debug run and indicates whether a trigger match B condition was met since arming. O Comparator B has not matched Comparator B match						
5 ARMF	Arm Flag — While DBGEN = 1, this status bit is a read-only image of ARM in DBGC. This bit is set by writing 1 to the ARM control bit in DBGC (while DBGEN = 1) and is automatically cleared at the end of a debug run. A debug run is completed when the FIFO is full (begin trace) or when a trigger event is detected (end trace). A debug run can also be ended manually by writing 0 to ARM or DBGEN in DBGC. 0 Debugger not armed 1 Debugger armed						
3:0 CNT[3:0]	FIFO Valid Count — These bits are cleared at the start of a debug run and indicate the number of words of valid data in the FIFO at the end of a debug run. The value in CNT does not decrement as data is read out of the FIFO. The external debug host is responsible for keeping track of the count as information is read out of the FIFO. 0000 Number of valid words in FIFO = No valid data 0001 Number of valid words in FIFO = 1 0010 Number of valid words in FIFO = 2 0011 Number of valid words in FIFO = 3 0100 Number of valid words in FIFO = 4 0101 Number of valid words in FIFO = 5 0110 Number of valid words in FIFO = 6 0111 Number of valid words in FIFO = 7 1000 Number of valid words in FIFO = 8						



Electrical Characteristics

A.3 Thermal Characteristics

This section provides information about operating temperature range, power dissipation, and package thermal resistance. Power dissipation on I/O pins is usually small compared to the power dissipation in on-chip logic and voltage regulator circuits and it is user-determined rather than being controlled by the MCU design. In order to take $P_{I/O}$ into account in power calculations, determine the difference between actual pin voltage and V_{SS} or V_{DD} and multiply by the pin current for each I/O pin. Except in cases of unusually high pin current (heavy loads), the difference between pin voltage and V_{SS} or V_{DD} will be very small.

Rating	Symbol	Value	Unit
Operating temperature range (packaged)	T _A	T _L to T _H -40 to 85	°C
Thermal resistance 28-pin PDIP 28-pin SOIC 32-pin LQFP 44-pin LQFP 48-pin QFN	$\theta_{ extsf{JA}}$	75 70 72 70 82	°C/W

Table A-2. Thermal Characteristics

The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_{.I} = T_{\Delta} + (P_{D} \times \theta_{.I\Delta})$$
 Eqn. A-1

where:

 T_A = Ambient temperature, °C

 $\theta_{\rm IA}$ = Package thermal resistance, junction-to-ambient, °C/W

$$P_D = P_{int} + P_{I/O}$$

 $P_{int} = I_{DD} \times V_{DD}$, Watts — chip internal power

 $P_{I/O}$ = Power dissipation on input and output pins — user determined

For most applications, $P_{I/O} \ll P_{int}$ and can be neglected. An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = K \div (T_A + 273^{\circ}C)$$
 Eqn. A-2

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273^{\circ}C) + \theta_{JA} \times (P_D)^2$$
 Eqn. A-3

where K is a constant pertaining to the particular part. K can be determined from equation 3 by measuring P_D (at equilibrium) for a known T_A . Using this value of K, the values of P_D and T_J can be obtained by solving equations 1 and 2 iteratively for any value of T_A .





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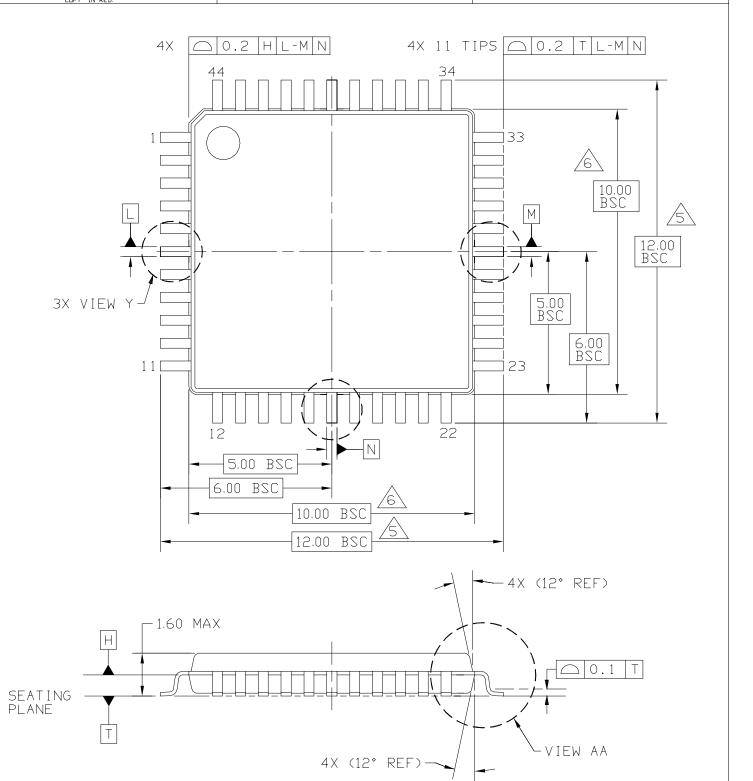
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44 LD TQFP, 10 X 10 PKG, 0.8 PITCH, 1.4 THICK CASE NUMBER: 824D-03

STANDARD: JEDEC MS-026-BCB

PACKAGE CODE: 8256

SHEET:

1 DF 3

